



Ordering Information

BV _{DSS} /	R _{DS(ON)}	$R_{DS(ON)}$ $I_{D(ON)}$ $V_{GS(th)}$		Order Number / Package
BV _{DGS}	(max)	(min)	(max)	TO-92
60V	3.0Ω	2A	2.0V	TN0106N3
100V	3.0Ω	2A	2.0V	TN0110N3

Features

- Low threshold 2.0V max.
- High input impedance
- Low input capacitance 50pF typical
- Fast switching speeds
- Low on resistance
- ☐ Free from secondary breakdown
- Low input and output leakage
- Complementary N- and P-channel devices

Applications

- Logic level interfaces ideal for TTL and CMOS
- Solid state relays
- Battery operated systems
- Photo voltaic drives
- Analog switches
- General purpose line drivers
- Telecom switches

Absolute Maximum Ratings

Drain-to-Source Voltage	BV_{DSS}
Drain-to-Gate Voltage	BV_{DGS}
Gate-to-Source Voltage	± 20V
Operating and Storage Temperature	-55°C to +150°C
Soldering Temperature*	300°C

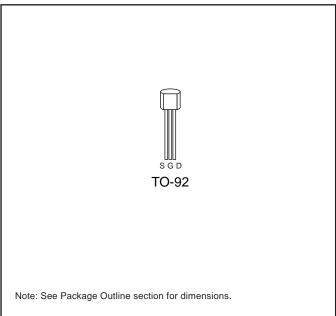
^{*} Distance of 1.6 mm from case for 10 seconds.

Low Threshold DMOS Technology

These low threshold enhancement-mode (normally-off) transistors utilize a vertical DMOS structure and Supertex's well-proven silicon-gate manufacturing process. This combination produces devices with the power handling capabilities of bipolar transistors and with the high input impedance and positive temperature coefficient inherent in MOS devices. Characteristic of all MOS structures, these devices are free from thermal runaway and thermally-induced secondary breakdown.

Supertex's vertical DMOS FETs are ideally suited to a wide range of switching and amplifying applications where very low threshold voltage, high breakdown voltage, high input impedance, low input capacitance, and fast switching speeds are desired.

Package Option



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Thermal Characteristics

Package	I _D (continuous)*	I _D (pulsed)	Power Dissipation @ T _C = 25°C	θ _{jc} °C/W	θ _{ja} °C/W	I _{DR} *	I _{DRM}
TO-92	350mA	2.0A	1.0W	125	170	350mA	2.0A

^{*} I_n (continuous) is limited by max rated T_j .

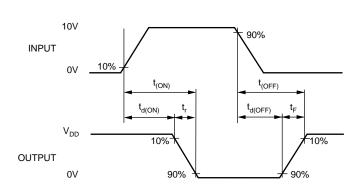
Electrical Characteristics (@ 25°C unless otherwise specified)

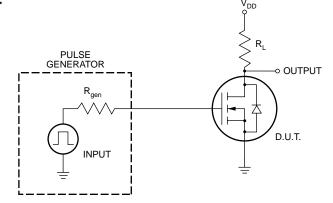
Symbol	Parameter		Min	Тур	Max	Unit	Conditions	
BV _{DSS}	Drain-to-Source	TN0110	100			V	$I_D = 1 \text{mA}, V_{GS} = 0 \text{V}$	
	Breakdown Voltage	TN0106	60				$I_D = IIIIA$, $V_{GS} = 0V$	
V _{GS(th)}	Gate Threshold Voltage		0.6		2.0	V	$V_{GS} = V_{DS}$, $I_D = 0.5 \text{mA}$	
$\Delta V_{GS(th)}$	Change in V _{GS(th)} with Temperature			-3.2	-5.0	mV/°C	$V_{GS} = V_{DS}$, $I_D = 1.0 \text{mA}$	
I _{GSS}	Gate Body Leakage				100	nA	$V_{GS} = \pm 20V, V_{DS} = 0V$	
I _{DSS}	I _{DSS} Zero Gate Voltage Drain Current				10		V _{GS} = 0V, V _{DS} = Max Rating	
					500	μΑ	$V_{GS} = 0V$, $V_{DS} = 0.8$ Max Rating $T_A = 125$ °C	
I _{D(ON)}	I _{D(ON)} ON-State Drain Current		0.75	1.4		А	$V_{GS} = 5V, V_{DS} = 25V$	
				3.4			$V_{GS} = 10V, V_{DS} = 25V$	
R _{DS(ON)}	Static Drain-to-Source			2.0	4.5		V _{GS} = 4.5V, I _D = 250mA	
	ON-State Resistance			1.6	3.0	Ω	V _{GS} = 10V, I _D = 500mA	
$\Delta R_{DS(ON)}$	Change in R _{DS(ON)} with Temperature			0.6	1.1	%/°C	I _D = 0.5A, V _{GS} = 10V	
G _{FS}	Forward Transconductance		225	400		m&	V _{DS} = 25V, I _D = 500mA	
C _{ISS}	Input Capacitance			50	60	pF		
C _{OSS}	Common Source Output Capacitance			25	35		$V_{GS} = 0V, V_{DS} = 25V$ f = 1 MHz	
C_{RSS}	Reverse Transfer Capacitance			4.0	8.0		1 = 1 1011 12	
t _{d(ON)}	Turn-ON Delay Time			2.0	5.0			
t _r	Rise Time Turn-OFF Delay Time			3.0	5.0	ns	$V_{DD} = 25V$ $I_{D} = 1.0A$ $R_{GEN} = 25\Omega$	
$t_{d(OFF)}$				6.0	7.0			
t _f	Fall Time			3.0	6.0		. GEN - 2000	
V _{SD}	Diode Forward Voltage Drop			1.0	1.5	V	$I_{SD} = 0.5A, V_{GS} = 0V$	
t _{rr}	Reverse Recovery Time			400		ns	$I_{SD} = 0.5A, V_{GS} = 0V$	

Notes:

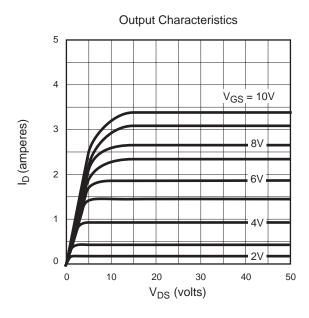
- 1. All D.C. parameters 100% tested at 25°C unless otherwise stated. (Pulse test: $300\mu s$ pulse, 2% duty cycle.)
- 2. All A.C. parameters sample tested.

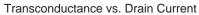
Switching Waveforms and Test Circuit

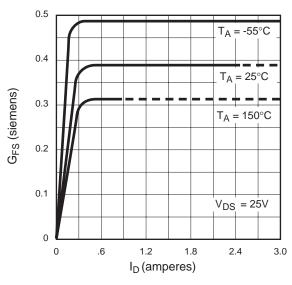




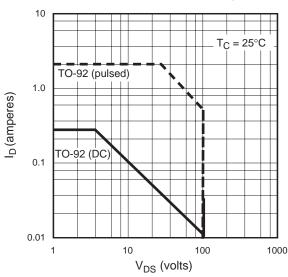
Typical Performance Curves



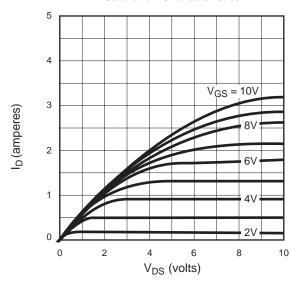




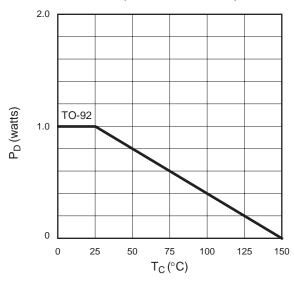
Maximum Rated Safe Operating Area



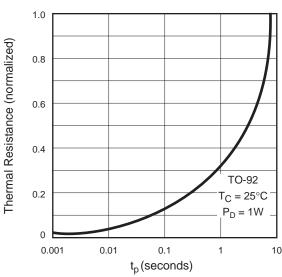
Saturation Characteristics



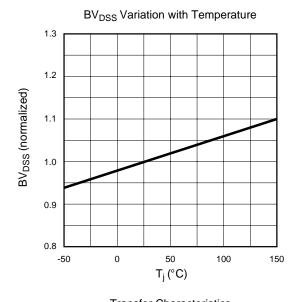
Power Dissipation vs. Case Temperature

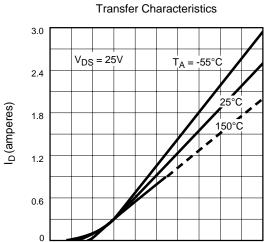


Thermal Response Characteristics



Typical Performance Curves



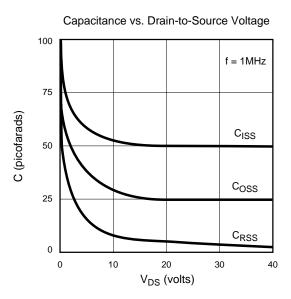


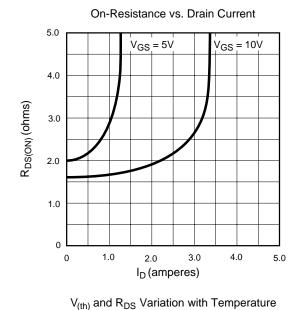
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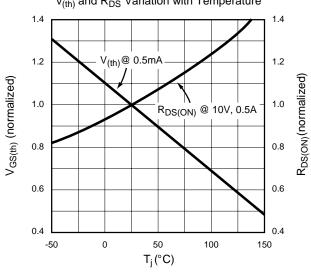
V_{GS} (volts)

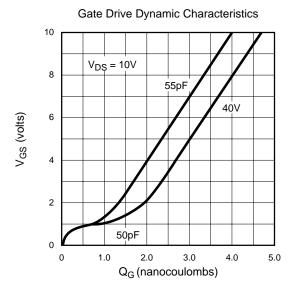
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